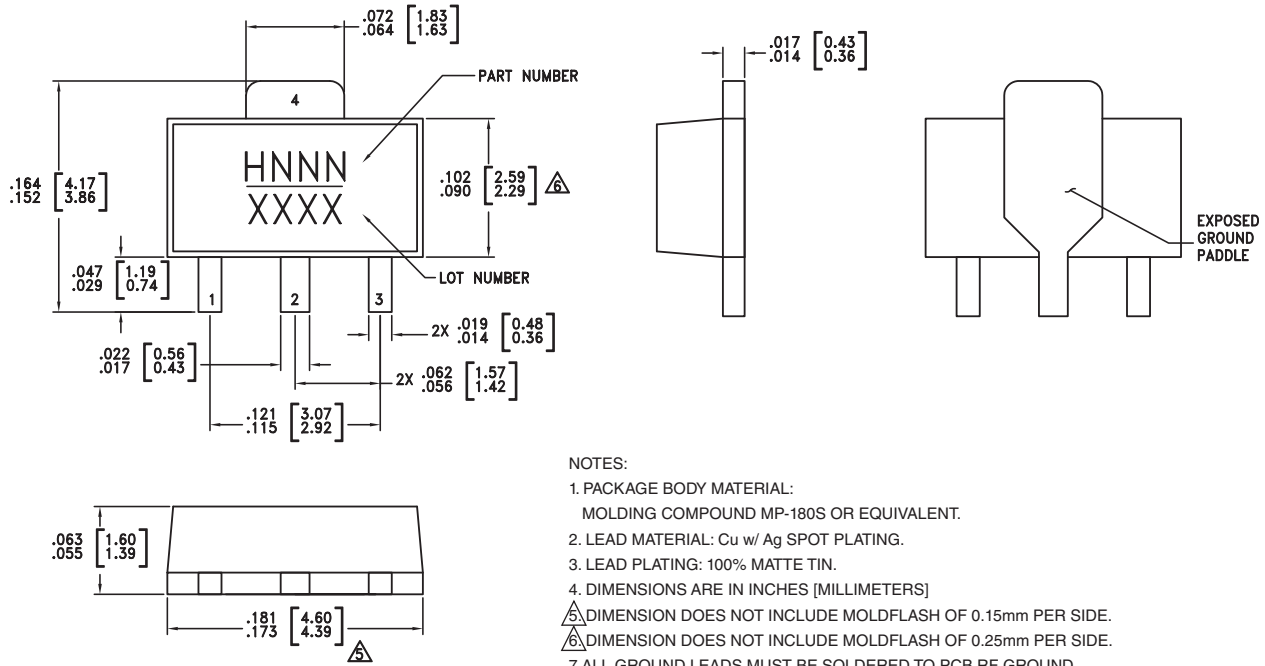




ST89 (E) – 4 LEAD PLASTIC SOT89 PACKAGE

ST89 (E) Package Outline Drawing



NOTES:

- PACKAGE BODY MATERIAL:
MOLDING COMPOUND MP-180S OR EQUIVALENT.
- LEAD MATERIAL: Cu w/ Ag SPOT PLATING.
- LEAD PLATING: 100% MATTE TIN.
- DIMENSIONS ARE IN INCHES [MILLIMETERS]
-  DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.15mm PER SIDE.
-  DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.25mm PER SIDE.
- ALL GROUND LEADS MUST BE SOLDERED TO PCB RF GROUND.

Package Information

Part Number Suffix	Package Body Material	Lead Finish	MSL Rating	Package Marking ^{[3][4]}
ST89	RoHS Compliant Mold Compound	Sn/Pb Solder	MSL1 ^[1]	HNNN XXXX
ST89E	RoHS Compliant Mold Compound	100% matte Sn	MSL1 ^[2]	HNNN XXXX

[1] Max peak reflow temperature of 235 °C

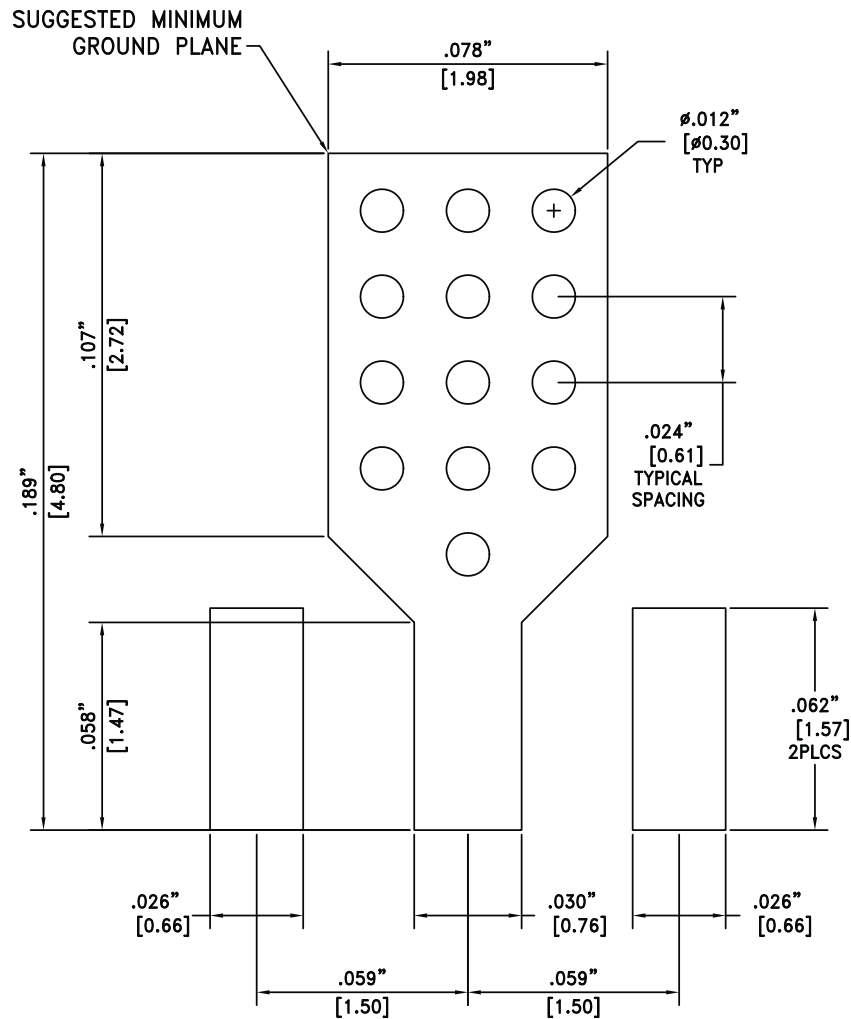
[2] Max peak reflow temperature of 260 °C

[3] 4-Digit lot number XXXX

[4] 3-Digit part number NNN

**ST89 (E) – 4 LEAD PLASTIC
SOT89 PACKAGE**

Suggested ST89 (E) PCB Land Pattern



NOTES:

1. DIMENSIONS ARE IN INCHES [MILLIMETERS].
2. PAD WIDTH SHOWN IS FOR SOLDERING ONLY. BEYOND SOLDERING AREA ALL CONDUCTORS THAT CARRY RF AND MICROWAVE SIGNALS SHOULD HAVE 50 OHM CHARACTERISTIC IMPEDANCE.